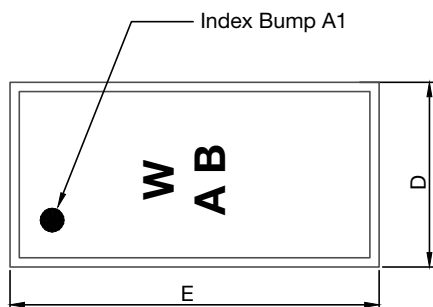
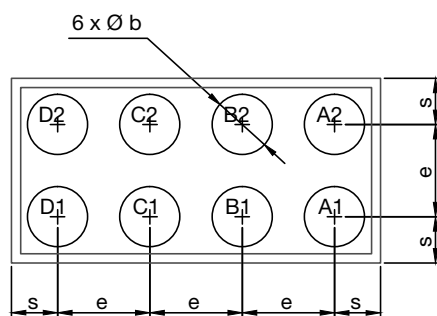


WCSP8: 8 Bumps

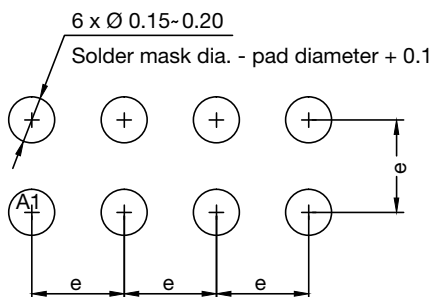
(2 x 4, 0.4 mm pitch, 233 μ m bump height, 0.8 mm x 1.6 mm die size)



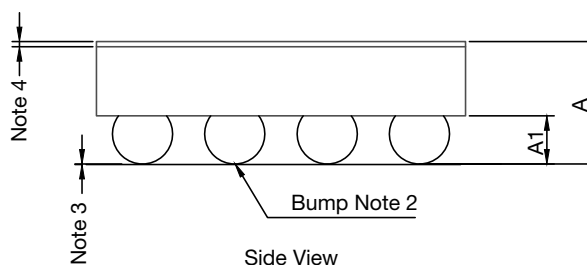
Top View



Bottom View



RECOMMENDED LAND PATTERN



Side View

DIMENSION	MILLIMETERS ⁽⁵⁾			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.515	0.530	0.545	0.0203	0.0209	0.0215
A1	0.183	0.208	0.233	0.0072	0.0082	0.0092
b	0.250	0.260	0.270	0.0098	0.0102	0.0106
e	0.400			0.0157		
s	0.160	0.180	0.200	0.0090	0.0098	0.0106
D	0.720	0.760	0.800	0.0283	0.0299	0.0315
E	1.520	1.560	1.600	0.0598	0.0614	0.0630

Notes (unless otherwise specified)

- (1) Laser mark on the silicon die back coated with an epoxy film.
- (2) Bumps are SAC396.
- (3) 0.050 max. co-planarity.
- (4) Laminate tape thickness is 0.022 mm.
- (5) Use millimeters as the primary measurement.

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